

SAFETY ORGANIZATIONS

THIS JACK HAS BEEN FORMALLY RECOGNIZED, CERTIFIED OR APPROVED BY THE LISTED AGENCY. THEREFORE, ALL TEST/REQUIREMENTS SPECIFIED IN THE LATEST REVISION OF THE FOLLOWING AGENCY STANDARDS HAVE BEEN MET.

UL RECOGNIZED
CSA CERTIFIED

UL 1863
CSA C22.2 No. 182.4

SPECIFICATIONS

CONTACTS

MATERIAL: PHOSPHOR BRONZE
PLATING: 50 MICROINCHES GOLD
BARRIER UNDERPLATING: 100 MICROINCHES NICKEL
RESISTANCE:
INITIAL: 20 MILLIOHMS MAXIMUM
AFTER DURABILITY TESTING
(500 MATING CYCLES): 30 MILLIOHMS MAXIMUM

FERRITES

TYPE: HIGH RESISTIVITY, NICKEL ZINC CERAMIC
BLOCK: MULTI-APERTURE RECTANGULAR PRISM

SHIELD MATERIAL

SOLDER-PLATED COPPER ALLOY

HOUSING MATERIAL

GLASS-FILLED POLYESTER (UL94V-0)

DIELECTRIC WITHSTANDING VOLTAGE

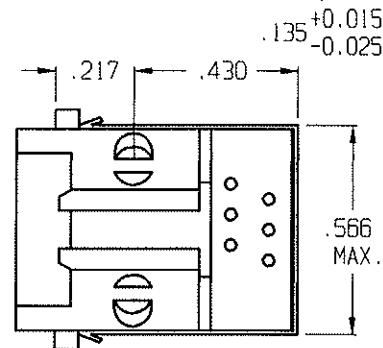
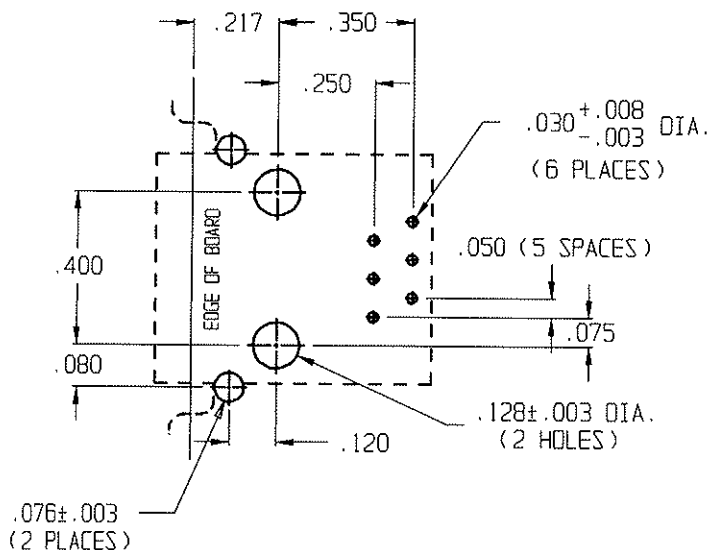
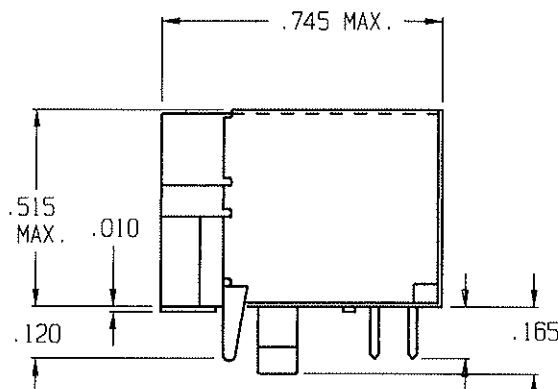
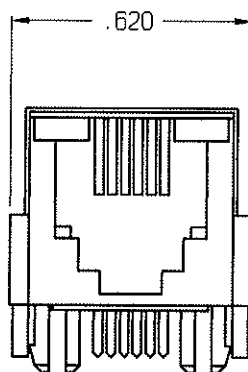
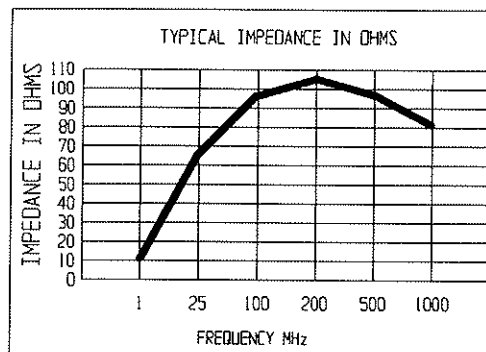
LINE-TO-LINE AND LINE-TO-GROUND 1000 VAC FOR 60 SECONDS

PRINTED CIRCUIT BOARD RETENTION

BEFORE SOLDERING: 1 LB. MINIMUM
AFTER SOLDERING: 20 LB. MINIMUM

CATALOG #RJ11-6N4-B

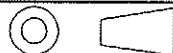
| ECN # | APPROV. | DATE |
|-------|---------|---------|
| 1 | MAC | 8-19-98 |



COMPLIES WITH FCC PART 68

PC BOARD LAYOUT

THIRD ANGLE
PROJECTION



UNLESS OTHERWISE SPECIFIED,
TOLERANCE TO BE $\pm .010$
MATERIAL & FINISH: AS SUPPLIED

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FILTERED MODULAR JACK

| CAD FILE: G:\CONRJ11GMB00 | | DATE: 8-14-98 | | CATALOG NO. | | REV. | |
|---------------------------|-------------|---------------|-----------|-------------|--|------|--|
| SCALE: NTS | DRW. BY: SD | DATE: 8-14-98 | ORIG: MAC | RJ11-6N4-B | | 00 | |

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